

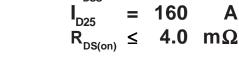
Advance Technical Information

TrenchMV[™] **Power MOSFET**

IXTF280N055T

(Electrically Isolated Back Surface)

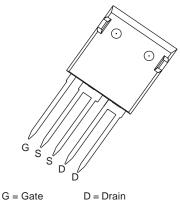
N-Channel Enhancement Mode Avalanche Rated



$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Symbol	nbol Test Conditions		Maximum Ratings	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	V _{DSS}			V	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	V _{DGR}	$I_J = 25^{\circ}\text{C to } 175^{\circ}\text{C}; R_{GS} = 1 \text{ M}\Omega$	55	V	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	V _{GSM}	Transient	± 20	V	
$\begin{array}{llllllllllllllllllllllllllllllllllll$		$T_{c} = 25^{\circ}C$	160	Α	
$\begin{array}{llllllllllllllllllllllllllllllllllll$	1	Package Current Limit, RMS (75 A per lead	d) 150	Α	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	I _{DM}	$T_{\rm C} = 25^{\circ}$ C, pulse width limited by $T_{\rm JM}$	600	Α	
$ \begin{array}{llllllllllllllllllllllllllllllllllll$	I	$T_{c} = 25^{\circ}C$	40	Α	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	É _{AS}	$T_{c}^{\circ} = 25^{\circ}C$	1.5	J	
$ \begin{array}{cccccccccccccccccccccccccccccccccccc$			3	V/ns	
$ \begin{array}{cccccccccccccccccccccccccccccccccccc$	P _D	T _c = 25°C	200	W	
$ \begin{array}{cccccccccccccccccccccccccccccccccccc$	Τ.		-55 +175	°C	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	T.,,		175	°C	
$ \begin{array}{cccccccccccccccccccccccccccccccccccc$	T _{stg}		-55 +175	°C	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		1.6 mm (0.062 in.) from case for 10 s	300	°C	
$ m V_{ISOL}$ 50/60 Hz, t = 1 minute, I $_{ISOL}$ < 1 mA, RMS 2500 V $ m F_{c}$ Mounting force 20120/4.525 N/lb.	_		260	°C	
F _c Mounting force 20120/4.525 N/lb.		$50/60 \text{ Hz}$, t = 1 minute, I_{ISOL} < 1 mA, RMS 250	00 V		
Weight 6 g		Mounting force 2	0120/4.525	N/lb.	
	Weight		6	g	

SymbolTest ConditionsCharacteristics $(T_J = 25^{\circ}\text{C} \text{ unless otherwise specified})$ Min.		 tic Values Max.	
BV _{DSS}	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	55	V
V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.0	4.0 V
I _{GSS}	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$		± 200 nA
I _{DSS}	$V_{DS} = V_{DSS}$ $V_{GS} = 0 V$	T _J = 150°C	5 μA 250 μA
R _{DS(on)}	$V_{GS} = 10 \text{ V}, I_D = 50 \text{ A}, \text{ Notes}$	s 1, 2	4.0 m Ω

ISOPLUS i4-Pak™ (5-lead) (IXTF)



S = Source

Features

- Ultra-low On Resistance
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
- easy to drive and to protect
- 175 °C Operating Temperature

Advantages

- Easy to mount
- Space savings
- High power density

Applications

- Automotive
 - Motor Drives
 - High Side Switch
 - 12V Battery
 - ABS Systems
- DC/DC Converters and Off-line UPS
- Primary- Side Switch
- High Current Switching Applications

DS99686 (01/07)

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Symbol	Test Conditions	Characteristic Values (T ₁ = 25°C unless otherwise specified)		
		Min.	Тур.	Max.
\mathbf{g}_{fs}	$V_{DS} = 10 \text{ V}; I_{D} = 60 \text{ A}, \text{ Note 1}$	70	110	S
C _{iss}			9800	pF
C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MH}$	Ηz	1450	pF
C _{rss}			320	pF
t _{d(on)}			32	ns
t _r	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \text{ V}_{DSS}, I_{D} = 0.5 \text{ V}_{DSS}$	= 50 A	55	ns
t _{d(off)}	$R_{_G} = 3.3 \Omega \text{ (External)}$		49	ns
t _f			37	ns
$\mathbf{Q}_{\mathrm{g(on)}}$			200	nC
\mathbf{Q}_{gs}	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \text{ V}_{DSS}, I_{D} =$	25 A	50	nC
\mathbf{Q}_{gd}			50	nC
R _{thJC}				0.75 °C/W
R _{thCH}			0.15	°C/W

Source-Drain Diode

Characteristic Values

T₁ = 25°C unless otherwise specified)

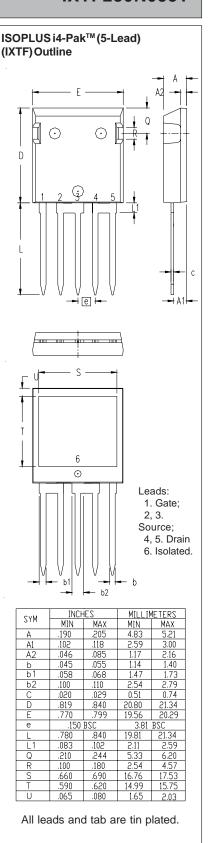
Symbol	Test Conditions	Min.	Тур.	Max.	
Is	$V_{GS} = 0 V$			150	Α
SM	Pulse width limited by $T_{_{\rm JM}}$			600	Α
V _{SD}	$I_F = 50 \text{ A}, V_{GS} = 0 \text{ V}, \text{ Note 1}$			1.0	V
t _{rr}	$I_F = 25 \text{ A}, -di/dt = 100 \text{ A}/\mu\text{s}$		40		ns
	$V_{R} = 25 \text{ V}, V_{GS} = 0 \text{ V}$				

Notes: 1. Pulse test: $t \le 300 \,\mu s$, duty cycled $\le 2 \,\%$;

2. Drain and Source Kelvin contacts must be located less than 5 mm from the plastic body.

ADVANCETECHNICALINFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.



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IXYSMOSFETs and IGBTs are covered by 6,404,065B1 4,835,592 5,049,961 5,237,481 6,162,665 6,683,344 6,727,585 7,005,734B2 one or more of the following U.S. patents: 4,850,072 4,881,106 5,017,508 5,063,307 5,187,117 5,381,025 5,486,715 6,259,123 B1 6,306,728 B1 6.534.343 6,710,405B2 6,710,463 6,759,692 6771478B2 7,063,975B2 7,071,537 6,583,505 5,034,796